

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Currently amended) A photosensitive resin composition comprising:

(A) a polymer having an acid functional group and/or a substituent derived therefrom;

(B) a compound represented by the general formula (10):



wherein X represents an n-valent organic group, n represents an integer of 2 to 6,
and each of R₄ and R₅ represents hydrogen or a monovalent organic group,
~~having at least one substituent derived from an amine functional group, wherein said~~
~~at least one of said monovalent organic groups~~
substituent is selected from the group
 consisting of:



wherein R₃ represents a monovalent organic group; X₃ represents an oxygen, sulfur, or nitrogen atom; and n represents 1 when X₃ is an oxygen atom or a sulfur atom, or n represents 2 when X₃ is a nitrogen atom;

(C) a photoreactive compound; and

(D) a solvent,

wherein said polymer (A) is a polyimide precursor, a polyimide, a polybenzoxazole precursor, a polybenzoxazole, a copolymer thereof, or a mixture thereof.

2. (Original) The photosensitive resin composition according to claim 1, wherein the compound of the component (B) further has at least one acid functional group and/or substituent derived therefrom.

3. and 4. (Cancelled).

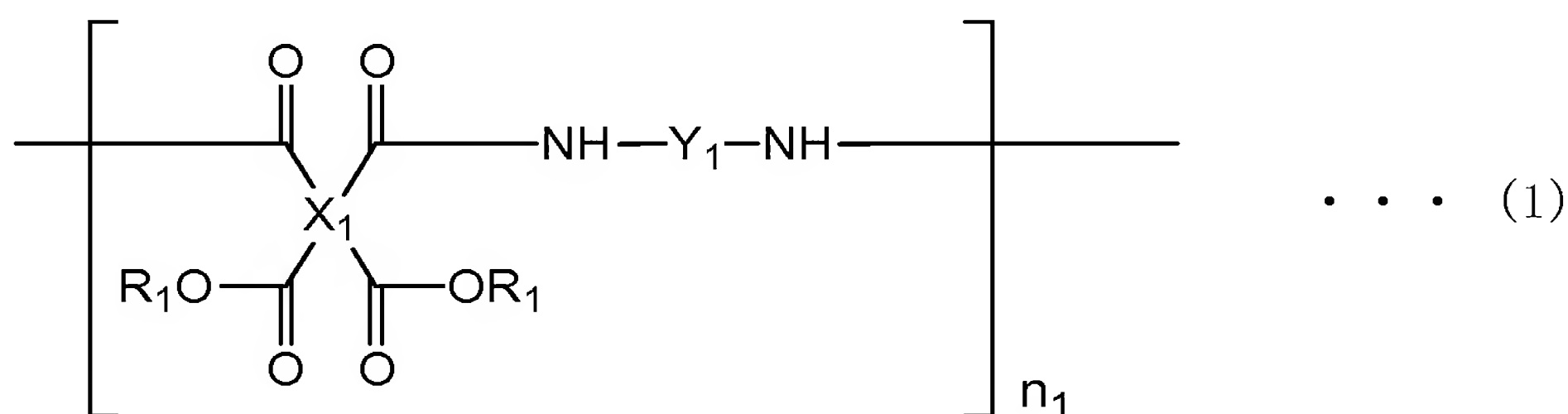
5. (Original) The photosensitive resin composition according to claim 1, wherein the component (A) further has at least one substituent derived from an amine functional group in itself or in another component (A), and wherein the component (B) further has at least one acid functional group and/or substituent derived therefrom.

6. (Original) The photosensitive resin composition according to claim 5, wherein the component (A) has one substituent derived from an amine functional group, and wherein the component (B) has one substituent or two substituents derived from an amine functional group and has one acid functional group and/or substituent derived therefrom.

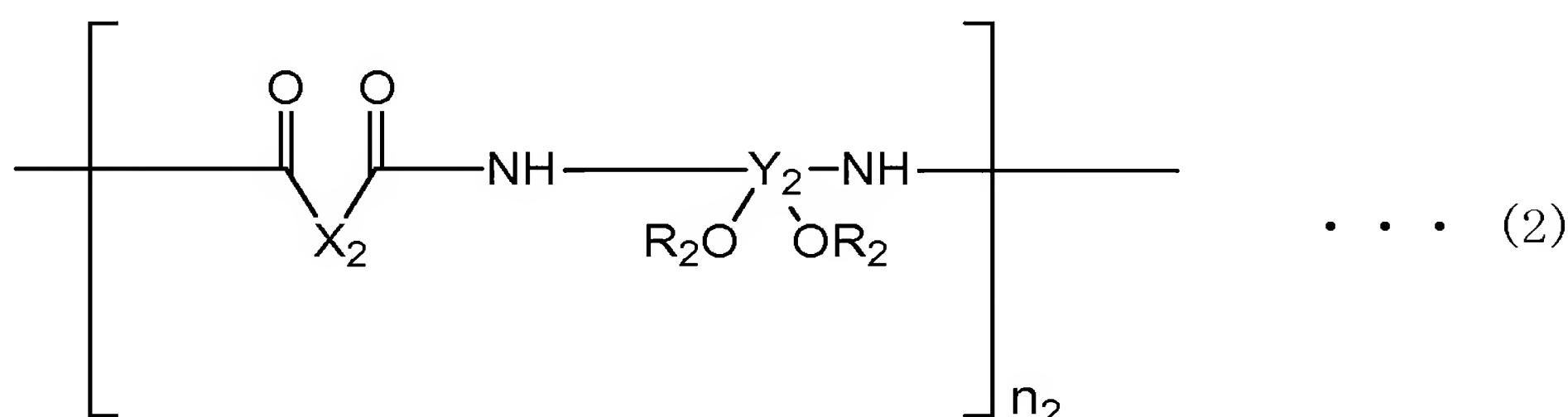
7. (Original) The photosensitive resin composition according to claim 1, wherein the polymer (A) is a heat-resistant polymer.

8. (Original) The photosensitive resin composition according to claim 1, wherein the acid functional group in the polymer (A) is a carboxyl group and/or a phenolic hydroxyl group.

9. (Previously presented) The photosensitive resin composition according to claim 7, wherein the heat-resistant polymer is a polyimide precursor represented by the general formula (1) below or polyimide derived from the precursor, a polybenzoxazole precursor represented by the general formula (2) below or polybenzoxazole derived from the precursor, a copolymer thereof, or a mixture thereof:



wherein X_1 represents a tetravalent organic group, Y_1 represents a divalent organic group, R_1 represents hydrogen or a monovalent organic group, and n_1 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer,



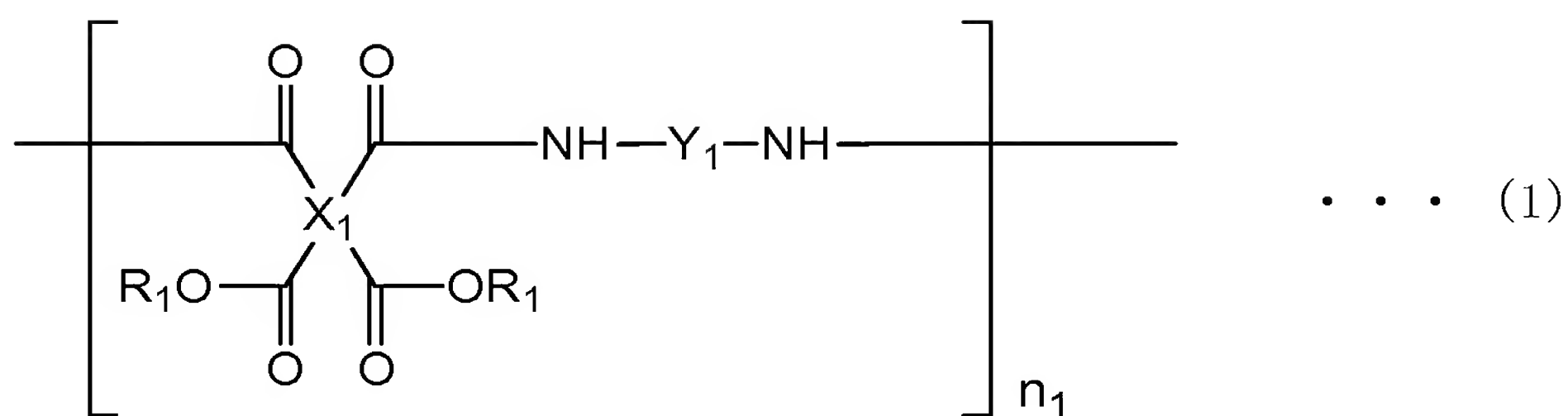
wherein X_2 represents a divalent organic group, Y_2 represents a tetravalent organic group, of which two valences are used in bonding to hydroxyl groups, R_2 represents

hydrogen or a monovalent organic group, and n_2 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer.

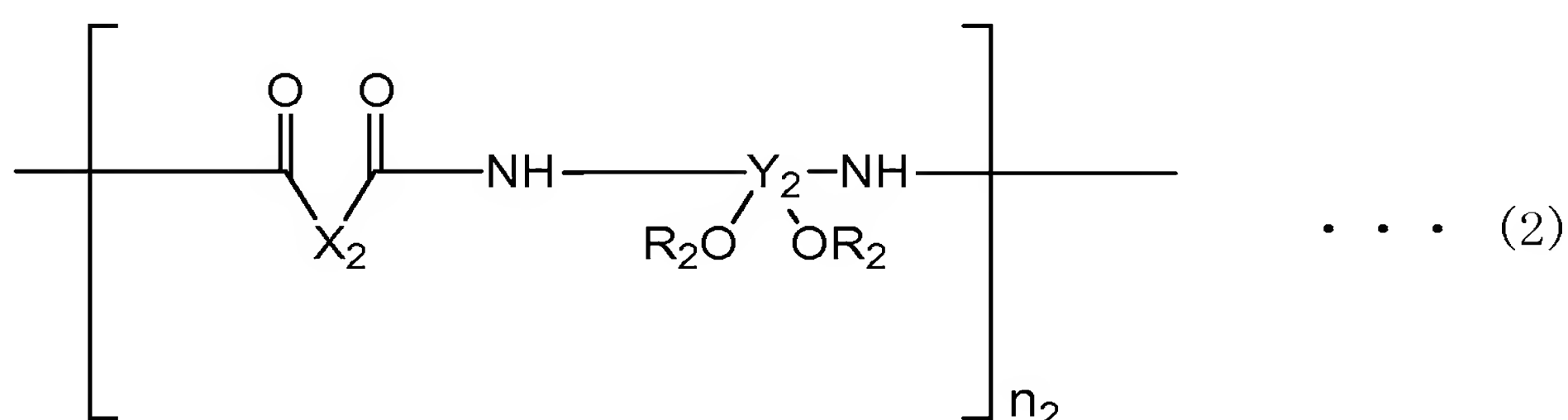
10. (Original) A method for forming a pattern, comprising:
- a step of applying the photosensitive resin composition according to claim 1 onto a substrate and drying it;
 - a step of subjecting the applied and dried photosensitive resin film to light exposure;
 - a step of subjecting the exposed photosensitive resin film to development using an alkaline aqueous solution; and
 - a step of subjecting the pattern obtained in the development to heat treatment.

11. (Original) An electronic part having an electronic device having the pattern obtained by the method according to claim 10, wherein the pattern is an interlayer dielectric layer and/or a surface protecting film layer.

12. (Previously presented) The photosensitive resin composition according to claim 8, wherein the heat-resistant polymer is a polyimide precursor represented by the general formula (1) below or polyimide derived from the precursor, a polybenzoxazole precursor represented by the general formula (2) below or polybenzoxazole derived from the precursor, a copolymer thereof, or a mixture thereof:



wherein X_1 represents a tetravalent organic group, Y_1 represents a divalent organic group, R_1 represents hydrogen or a monovalent organic group, and n_1 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer,



wherein X_2 represents a divalent organic group, Y_2 represents a tetravalent organic group, of which two valences are used in bonding to hydroxyl groups, R_2 represents hydrogen or a monovalent organic group, and n_2 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer.

13. (Previously presented) The photosensitive resin composition according to claim 1, wherein said R_3 is a monovalent organic group having 1 to 20 carbon atoms.

14. (Previously presented) The photosensitive resin composition according to claim 1, wherein said compound of the component (B) serves as a chain extender capable of increasing molecular weight of said polymer of the component (A) during a heat treatment of the photosensitive resin composition.

15. (Previously presented) The photosensitive resin composition according to claim 1, which contains 0.05 to 50 parts by weight of said compound of the component (B) relative to 100 parts by weight of said polymer of the component (A).

16. (Previously presented) The photosensitive resin composition according to claim 1, which contains 0.2 to 20 parts by weight of said compound of the component (B) relative to 100 parts by weight of said polymer of the component (A).

17. (New) The photosensitive resin composition according to claim 1, wherein said polymer (A) has an acid functional group.

18. (New) The photosensitive resin composition according to claim 1, wherein R_3 is selected from the group consisting of methyl, ethyl, propyl, isopropyl, n-butyl, s-butyl, t-butyl, cyclopropenyl, cyclobutyl, cyclopentyl, cyclohexyl, cyclohexylmethyl, cyclohexenyl, norbornyl, norbornenyl, adamantyl, benzyl, p-nitrobenzyl, trifluoromethyl, methoxymethyl, ethoxyethyl, methoxymethyl, ethoxymethyl, methoxyethoxymethyl, benzoxymethyl, ethoxytetrahydropyranyl, tetrahydrofuranyl, 2-trimethylsilylethoxymethyl, trimethylsilyl, t-butyldimethylsilyl, 3-

oxocyclohexyl, 9-fluorenylmethyl, methylthiomethyl, phenyl, toluyl, xylyl, 9,10-dihydroanthranyl, trimethylphenyl, pentamethylphenyl, biphenyl, terphenyl, quaterphenyl, dimethylbiphenyl, naphthalenyl, methylnaphthalenyl, fluorenyl, fluorophenyl, fluorobiphenyl, isopropylidenebiphenyl, tetrafluoroisopropylidenebiphenyl, benzyl phenyl ether, phenyl ether, phenoxytoluoyl, methoxybiphenyl, dimethoxybiphenyl, methoxynaphthalenyl, dimethoxynaphthalenyl, and nitrophenyl.